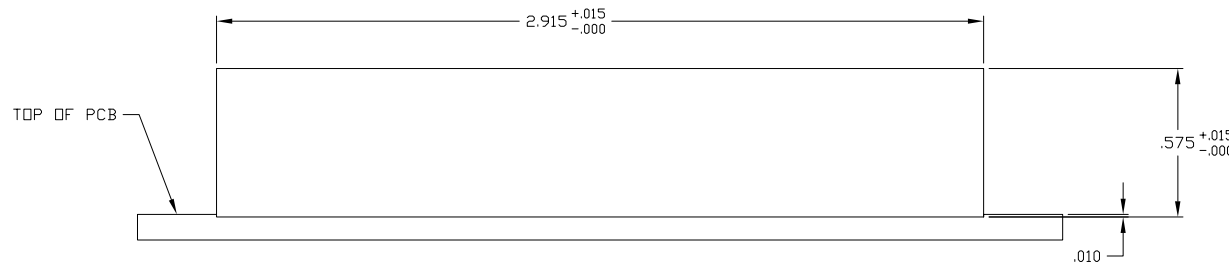
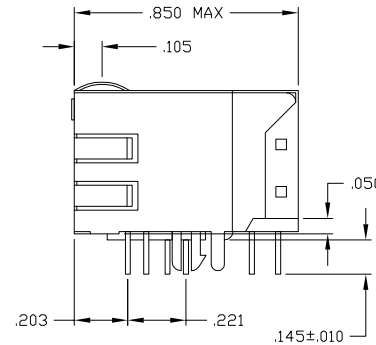
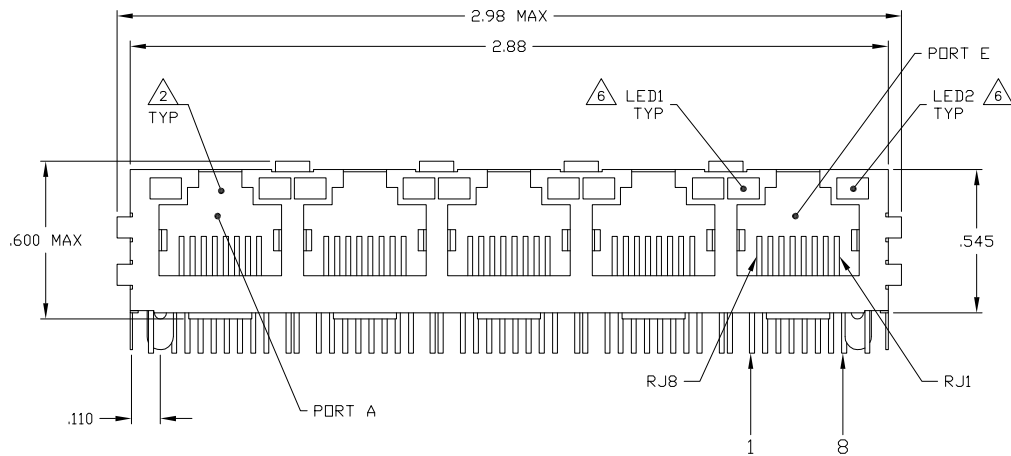
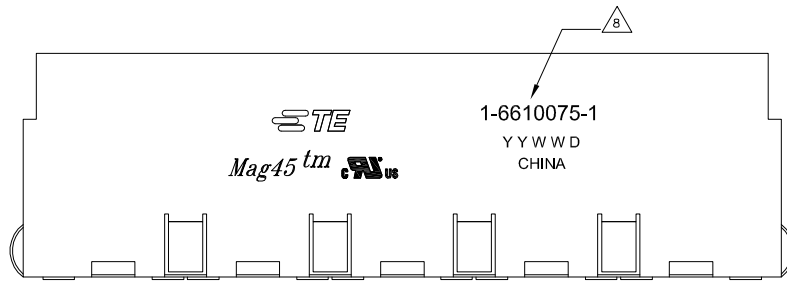


LOC	DATE	REVISIONS	DATE	BY	APP'D
AA	22				
B	REV PER ECO-08-016861		27JUN2008	QL	TX
B1	REVISED PER ECO-09-024927		11NOV09	KK	AEG
C	ECO-11-013348		20MAY2011	EL	LR

MECHANICAL:



1X5 SUGGESTED PANEL CUTOUT

- MATERIALS:
 - HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0.
 - SHIELD - .010" THICK, C26800 BRASS PREPLATED WITH 30μINCH MIN SEMI-BRIGHT NICKEL. SOLDER TABS POST DIPPED WITH 100μINCH MIN SAC SOLDER.
 - MOD JACK CONTACTS - 0.0157 X 0.018" PHOSPHOR BRONZE, 50μINCH MIN OVERALL NICKEL UNDERPLATE WITH SELECT 50μINCH MIN HARD GOLD FINISH PLATE. SOLDER TAILS WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP.
 - LIGHT EMITTING DIODE(LED) - DIFFUSED EPOXY LENS, .020" X .020" CARBON STEEL WIREFRAME LEADS PRE-PLATED WITH 80μINCH SILVER OVER 40μINCH NICKEL UNDERPLATE OVER 40μINCH COPPER UNDERPLATE. POST-PLATED WITH 100μIN MIN MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP.

- RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB PART F.

- MAGNETICS
 - IMPEDANCE: 100 OHMS
 - TURNS RATIO (CHIP-CABLE): TX = 1:1, RX = 1:1
 - OPEN CIRCUIT INDUCTANCE (OCL): 350μH MIN @100kHz, 0.1VRMS, 8mA DC BIAS FROM 0°C TO 70°C, TX AND RX
 - PERFORMANCE @ 25°C:
 - INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz
 - RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 30MHz
 - 18-20LOG(f/30)dB MIN FROM 30.1MHz TO 60MHz
 - 12dB MIN FROM 60.1MHz TO 80MHz
 - CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz
 - 33-20LOG(f/50)dB MIN FROM 40.1MHz TO 100MHz
 - COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
 - ISOLATION VOLTAGE: 2250VDC (MAX) FOR 60 SECONDS WITH A RISE TIME OF 500V/SEC AND WITH ALL PORTS CONNECTED.

- C1 IS AN OPTIONAL CAPACITOR. IF NO CAPACITOR, TRACE IS CONTINUOUS. SEE TABLE FOR PRESENCE OF CAPACITOR IN DIFFERENT CONFIGURATIONS.

- OPERATING TEMPERATURE: FROM 0° TO -70°C.

- LEDS WITH BUILT-IN RESISTOR
 - LEDS ARE DRIVEN WITH 5V VOLTAGE AND THE MAX OPERATING CURRENT IS 20mA.
 - LED COLOR : DOMINANT WAVELENGTH (λD): GREEN 568 nm TYP. @ VF=5V
 - FORWARD CURRENT (IF): GREEN 12 mA TYP. @ VF=5V
 - DOMINANT WAVELENGTH (λD): YELLOW 588 nm TYP. @ VF=5V
 - FORWARD CURRENT (IF): YELLOW 13 mA TYP. @ VF=5V

- INDICATED CONNECTIONS ARE FOR NIC CONFIGURATION. THE MAGNETICS ARE SYMMETRICAL, AND SUPPORT AUTO-MDI/MDIX.

- TE CONNECTIVITY LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.

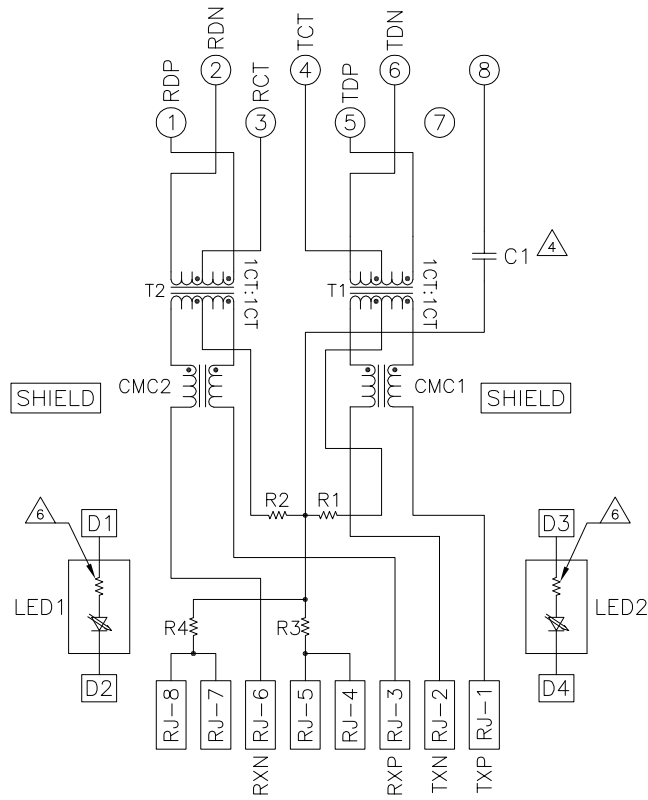
- THESE PARTS IS RECOMMENDED FOR WAVE SOLDERING PROCESS, PEAK WAVE SOLDERING TEMPERATURE IS 265°C MAX, 10 SECONDS MAX.

- OBsolete PARTS: OBSOLETE C15 STREAMLINING PER D.RENAUD/D.SINISI

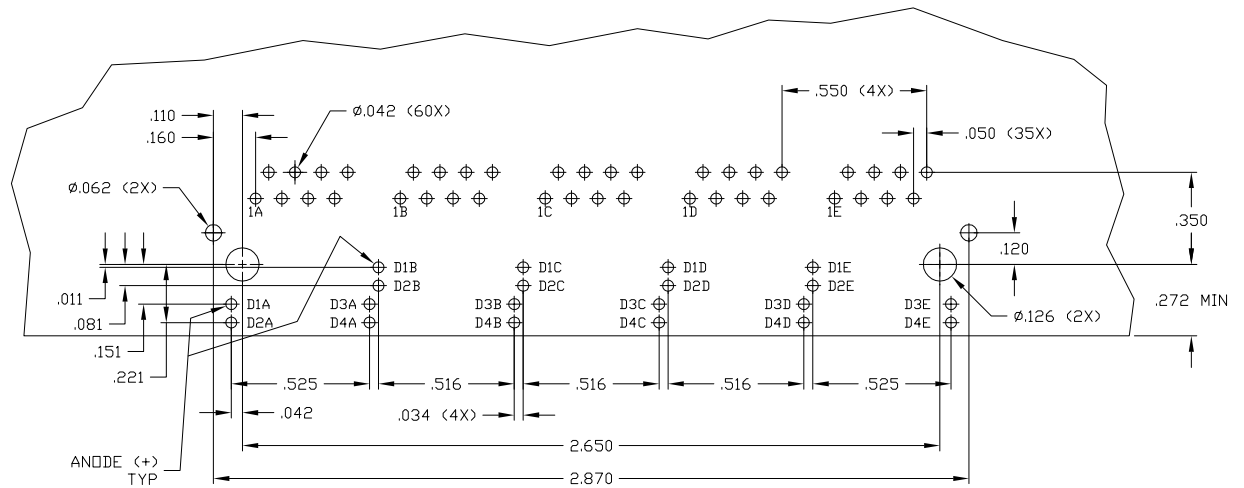
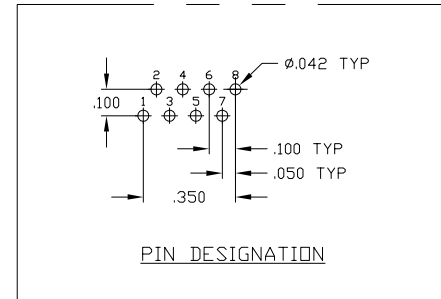
OBsolete	YES	GREEN	GREEN	6-6610075-1
	YES	GREEN	YELLOW	5-6610075-1
	NO	GREEN	GREEN	1-6610075-1
DECOUPLING CAPACITOR		LED1	LED2	PART NUMBER

DIMENSIONS:		INCHES		MILLIMETERS		TE Connectivity	
0 PAC ±	1 PAC ±	2 PAC ±	3 PAC ±	4 PAC ±	5 PAC ±	6 PAC ±	7 PAC ±
THIS DRAWING IS A CONTROLLED DOCUMENT.		VARIABLE - DIMENSIONS		DIMENSIONS		1X5 MAG45(TM) MODULAR JACK, 7N2 SCHEMATIC, 726 SERIES MAGNETIC CIRCUIT, SHIELDED, OPTIONAL DECOUPLING CAPACITOR, WITH RESISTOR LEADS	
MATERIAL		FINISH		WEIGHT		SCALE	
A1		00779		C=6610075		CUSTOMER DRAWING	


726 SERIES MAGNETIC CIRCUIT 



C1 = 1000 pF, 2kV DECOUPLING CAPACITOR
R1-R4 = 75 OHMS, 1/16W, 5% RESISTORS



SUGGESTED PCB LAYOUT
(Component Side)

THIS DRAWING IS A CONTROLLED DOCUMENT.		REV	1	DATE	17MAR2008	 TE Connectivity
DRAWN BY: J. VARELA - 17MAR2008		CHKD	J. VARELA - 17MAR2008			
DIMENSIONS: INCHES		TO DIMENSIONS UNLESS OTHERWISE SPECIFIED:		NAME	1X5 MAG45(TM) MODULAR JACK, 7N2 SCHEMATIC, 726 SERIES MAGNETIC CIRCUIT, SHIELDED, OPTIONAL DECOUPLING CAPACITOR, WITH RESISTOR LEADS	
0 P/C ± .010		1 P/C ± .010		PRODUCT SPEC	108-2100	
2 P/C ± .008		3 P/C ± .008		APPLICATION SPEC		
4 P/C ± .008		5 P/C ± .008		SIZE	CAGE CODE	DRAWING NO
MATERIAL		FINISH		WEIGHT	A1	00779
				CUSTOMER DRAWING	C=	6610075
				SCALE	NTS	SHEET 2 OF 2
				REV	C	